

NCE N-Channel Super Trench Power MOSFET

Description

The series of devices uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS(ON)}}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

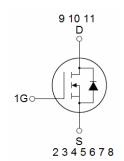
- DC/DC Converter
- •Ideal for high-frequency switching and synchronous rectification

General Features

- V_{DS} =40V, I_D =250A $R_{DS(ON)}$ =1.1m Ω , typical @ V_{GS} =10V
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 175 °C operating temperature
- Pb-free lead plating

100% UIS TESTED! 100% ΔVds TESTED!





Schematic Diagram

Package Marking and Ordering Information

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	Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
	NCEP40T20ALL	NCEP40T20ALL	TO-LL	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	40	V
Gate-Source Voltage	V _G S	±20	V
Drain Current-Continuous	I _D	250	Α
Drain Current-Continuous(T _C =100°C)	I _D (100℃)	175	А
Pulsed Drain Current (Note 1)	I _{DM}	1000	А
Maximum Power Dissipation	P _D	300	W
Derating factor		2.0	W/°C
Single pulse avalanche energy (Note 5)	E _{AS}	1692	mJ
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 175	$^{\circ}\mathbb{C}$

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	R _{θJC}	0.5	°C/W
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NCEP40T20ALL

Electrical Characteristics (T_C=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	1					•
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	40		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA
On Characteristics (Note 3)			L.			1
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_D=250\mu A$	2.0	3.0	3.8	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =100A	-	1.1	1.35	mΩ
Forward Transconductance	g fs	V _{DS} =5V,I _D =100A		90	-	S
Dynamic Characteristics (Note4)			•			•
Input Capacitance	C_{lss}	V 00V/V 0V	-	5834.6	-	PF
Output Capacitance	C _{oss}	$V_{DS}=20V, V_{GS}=0V,$	-	2320.5	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	70	-	PF
Switching Characteristics (Note 4)			•			•
Turn-on Delay Time	t _{d(on)}		-	14.5	-	nS
Turn-on Rise Time	t _r	V_{DD} =20 V,I_{D} =100 A	-	8	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =1.6 Ω	-	58	-	nS
Turn-Off Fall Time	t _f		-	10	-	nS
Total Gate Charge	Qg	V 00VI 400A	-	91	-	nC
Gate-Source Charge	Q _{gs}	$V_{DS}=20V,I_{D}=100A,$	-	29.4		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	19		nC
Drain-Source Diode Characteristics			•		•	
Diode Forward Voltage (Note 3)	V_{SD}	V _{GS} =0V,I _S =100A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	250	Α
Reverse Recovery Time	t _{rr}	$T_J = 25^{\circ}C$, $I_F = I_S$	-	-	38	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	-	125	nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,VDD=20V,VG=10V,L=0.5mH,Rg=25 Ω





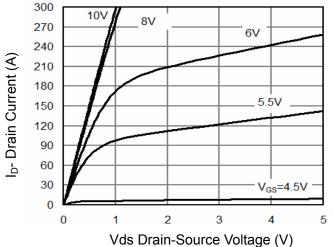


Figure 1 Output Characteristics

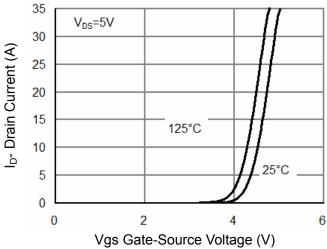


Figure 2 Transfer Characteristics

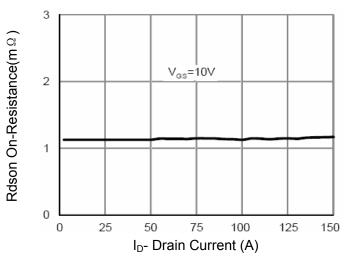


Figure 3 Rdson- Drain Current

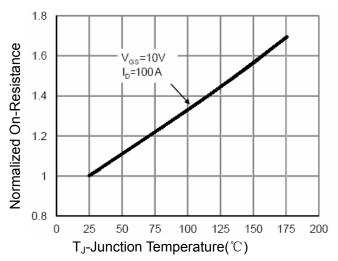


Figure 4 Rdson-Junction Temperature

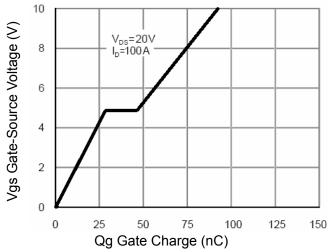


Figure 5 Gate Charge

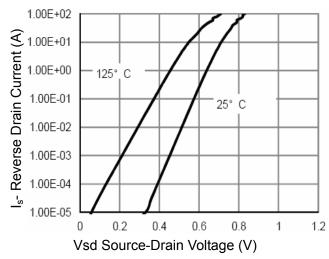


Figure 6 Source- Drain Diode Forward



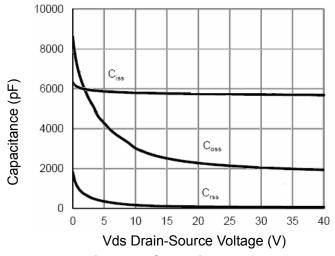


Figure 7 Capacitance vs Vds

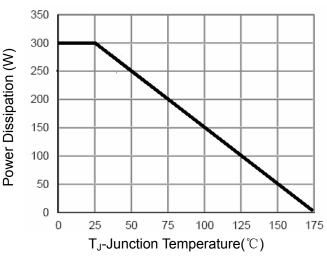


Figure 9 Power De-rating

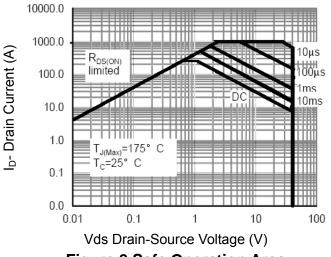


Figure 8 Safe Operation Area

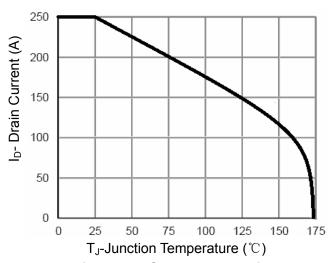


Figure 10 Current De-rating

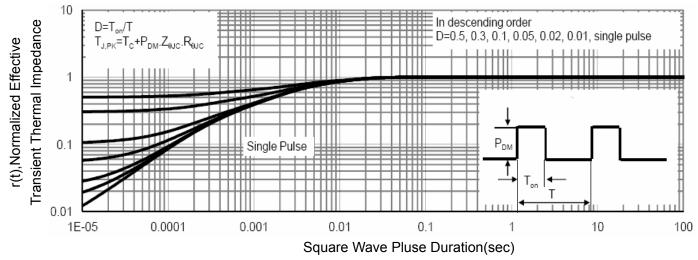
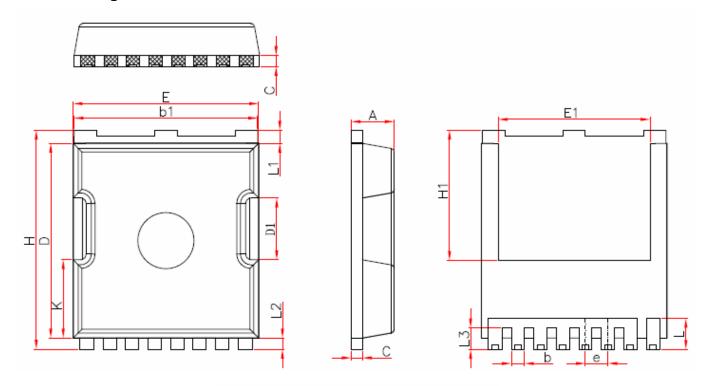


Figure 11 Normalized Maximum Transient Thermal Impedance



TOLL Package Information



Symbo1	Mi	ers	
	Min.	Nom.	Max.
A	2.20	2.30	2.40
b	0.65	0.75	0.85
b1	9.70	9.80	9.90
С	0.50	0.60	0.70
D	10.30	10.40	10.50
D1	3.15	3.3	3. 45
Е	9.70	9.90	10.10
E1	8.00	8. 10	8.20
е	1.10	1.20	1.30
Н	11.6	11.7	11.8
H1	6.85	6.95	7.05
K	4.08	4.18	4. 28
L	1.60	1.65	2.10
L1	0.60	0.70	0.80
L2	0.50	0.60	0.70
L3	1.05	1.20	1.30

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